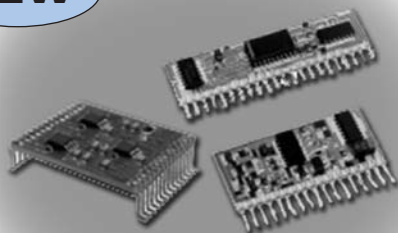


NEW



features

- Adjustment processes are decreased by function and ratio trimmings
- High density mounting by bonding (COB)
- Various types of package are available
- High reliability achieved by KOA's original thick film technology
- Thick film printed circuit substrate applies the non-noble metal paste (conductive paste and resistive paste) and receives the many total inquires including material selecting, pattern designing and mass production

NEW

ordering information

New Part #	KA	7777	D
	Product Code	KOA Ref. Number	Terminal Surface Material
	KA: Hybrid IC SC: Non-Noble		D: SnAgCu T: Sn

Component - KA/CB Series

Substrate Materials	Item	Printing	Mounting	Bonding
	Al ₂ O ₃ Alumina	o	o	o
	Glass epoxy	x	o	o
Conductors, Resistors	Item	Ag-Pd	Ag-Pt	Cu
	Conductor resistance	18mΩ/□/15μm	5mΩ/□/10μm	2mΩ/□/20μm
	Heat shock	-55°C~+125°C 300 Cycles	-55°C~+125°C 500 Cycles	-55°C~+125°C 500 Cycles
	RuO ₂	5Ω~10MΩ ±100x10 ⁻⁶ /K		10Ω~1MΩ ±100x10 ⁻⁶ /k
Mounting	Item	Specifications		
	COB	Au Wire, Al Wire		
	BGA	0.8mm Pitch~		
	QFP	0.4mm Pitch~		
	Chip	0.6mm x 0.3mm (0.4mm x 0.2mm)~		
Package, Outside Terminals	Package	Lead Pitch		
	SIP	1.8mm, 2.0mm, 2.5mm, 2.54mm		
	DIP, SOP	1.27mm, 1.8mm, 2.54mm		
	ZIP	2.54mm		
Over Coating, Plating	Over Coating	Color		UL Standard
	Epoxy metamorphic phenol	Black		94 V0 Approved
	Epoxy	Black		94 V1 Approved

o= Available x= Not available

modules